

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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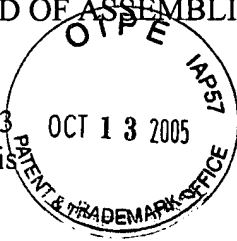
Applicant: Brian Taggart et al.

Title: BOND FINGER ON VIA SUBSTRATE, PROCESS OF MAKING SAME, PACKAGE MADE THEREBY, AND METHOD OF ASSEMBLING SAME

Docket No.: 884.853US1

Filed: June 30, 2003

Examiner: Jeremy Norris



Serial No.: 10/612,281

Due Date: November 8, 2005

Group Art Unit: 2841

MS Amendment

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

We are transmitting herewith the following attached items (as indicated with an "X"):

☒ Return postcard.

☒ Amendment and Response Under 37 CFR 1.111 (13 pgs.).

If not provided in a separate paper filed herewith, Please consider this a PETITION FOR EXTENSION OF TIME for sufficient number of months to enter these papers and please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

Customer Number 21186

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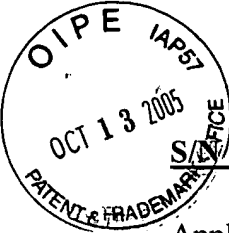
CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: MS Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 11th day of October, 2005.

John D. Gustaf-Wrathell
Name

Signature

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

(GENERAL)



S/N 10/612,281

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Brian Taggart et al.	Examiner:	Jeremy Norris
Serial No.:	10/612,281	Group Art Unit:	2841
Filed:	June 30, 2003	Docket No.:	884.853US1
Title:	BOND FINGER ON VIA SUBSTRATE, PROCESS OF MAKING SAME, PACKAGE MADE THEREBY, AND METHOD OF ASSEMBLING SAME		
Assignee:	Intel Corporation	Customer No:	21186

AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

MS Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

This responds to the Office Action mailed on August 8, 2005. Please amend the above-identified patent application as follows.